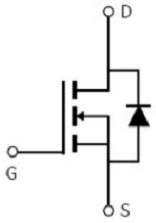
Main Product Characteristics:

V_{DSS}	60V
R_{DS}(on)	10mohm(typ.)
I_D	60A

TO220

Marking and pin Assignment



Schematic diagram

Features and Benefits:

- Advanced trench MOSFET process technology
- Special designed for PWM, load switching and general purpose applications
- Ultra low on-resistance with low gate charge
- Fast switching and reverse body recovery
- 175℃ operating temperature

Description:

It utilizes the latest trench processing techniques to achieve the high cell density and reduces the on-resistance with high repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in power switching application and a wide variety of other applications

Absolute max Rating:

Symbol	Parameter	Max.	Units
I_D @ TC = 25°C	Continuous Drain Current, V_{GS} @ 10V①	60	A
I_D @ TC = 100°C	Continuous Drain Current, V_{GS} @ 10V①	48	
I_{DM}	Pulsed Drain Current②	240	
P_D @TC = 25°C	Power Dissipation③	115	W
	Linear Derating Factor	0.74	W/°C
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy @ L=0.1mH	235	mJ
I_{AS}	Avalanche Current @ L=0.1mH	68	A
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 175	°C

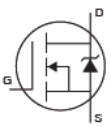
Thermal Resistance

Symbol	Characterizes	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-case③	—	1.5	℃/W
$R_{\theta JA}$	Junction-to-ambient (t ≤ 10s) ④	—	62	℃/W
	Junction-to-Ambient (PCB mounted, steady-state) ④	—	40	℃/W

Electrical Characterizes @T_A=25℃ unless otherwise specified

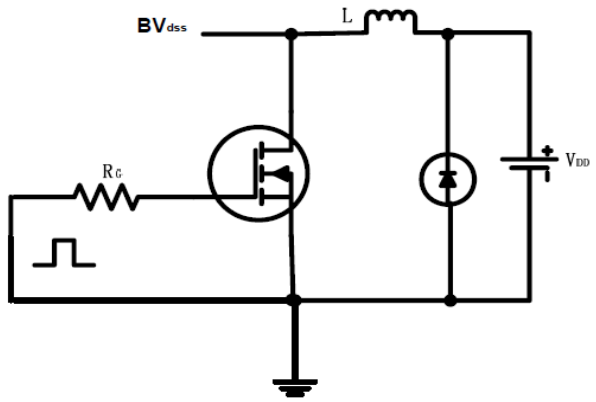
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source breakdown voltage	60	—	—	V	V_{GS} = 0V, ID = 250μA
$R_{DS(on)}$	Static Drain-to-Source on-resistance	—	10	14	mΩ	V_{GS}=10V,I_D =30A
		—	17	—		T_J = 125℃
$V_{GS(th)}$	Gate threshold voltage	2	—	4	V	V_{DS} = V_{GS}, I_D = 250μA
		—	2.53	—		T_J = 125℃
I_{DSS}	Drain-to-Source leakage current	—	—	1	μA	V_{DS} = 60V,V_{GS} = 0V
		—	—	50		T_J = 125°C
I_{GSS}	Gate-to-Source forward leakage	—	—	100	nA	V_{GS} =20V
		-100	—	—		V_{GS} = -20V
Q_g	Total gate charge	—	62	—	nC	V_{DS}=30V,
Q_{gs}	Gate-to-Source charge	—	17	—		I_D=30A,
Q_{gd}	Gate-to-Drain("Miller") charge	—	20	—		V_{GS}=10V
$t_{d(on)}$	Turn-on delay time	—	16	—	ns	V_{GS}=10V, VDS=30V,
t_r	Rise time	—	13	—		R_{GEN}=2.55Ω, I_D=2A
$t_{d(off)}$	Turn-Off delay time	—	38.5	—		
t_f	Fall time	—	8.6	—		
C_{iss}	Input capacitance	—	3265	—	pF	V_{GS} = 0V
C_{oss}	Output capacitance	—	173	—		V_{DS} = 25V
C_{rss}	Reverse transfer capacitance	—	163	—		f = 1MHz

Source-Drain Ratings and Characteristics

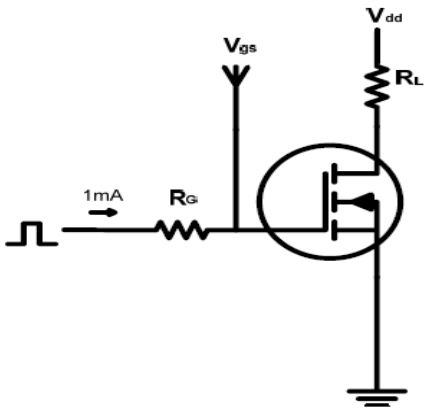
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	60	A	MOSFET symb showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode)	—	—	240	A	
V_{sd}	Diode Forward Voltage	—	0.9	1.3	V	I_S=40A, V_{GS}=0V
t_{rr}	Reverse Recovery Time	—	24.3	—	ns	T_J = 25°C, I_F =60A,
Q_{rr}	Reverse Recovery Charge	—	26.5	—	nC	di/dt = 100A/μs

Test circuits and Waveforms

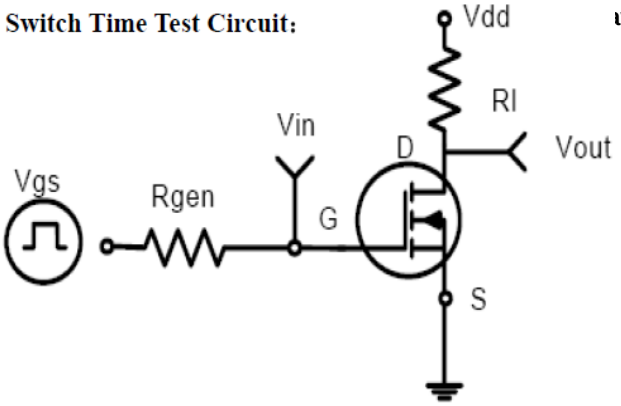
EAS test circuits:



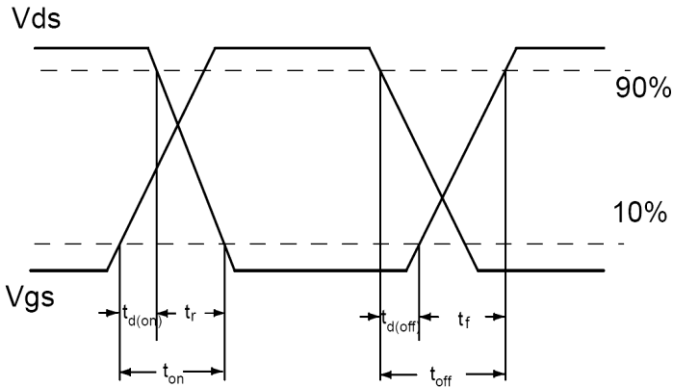
Gate charge test circuit:



Switch Time Test Circuit:



ıveforms:



Notes:

①The maximum current rating is limited by bond-wires.

②Repetitive rating; pulse width limited by max. junction temperature.

③The power dissipation PD is based on max. junction temperature, using junction-to-case thermal resistance.

④The value of $R_{\theta JA}$ is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with TA =25°C

⑤These curves are based on the junction-to-case thermal impedence which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=175°C.

Typical electrical characteristics

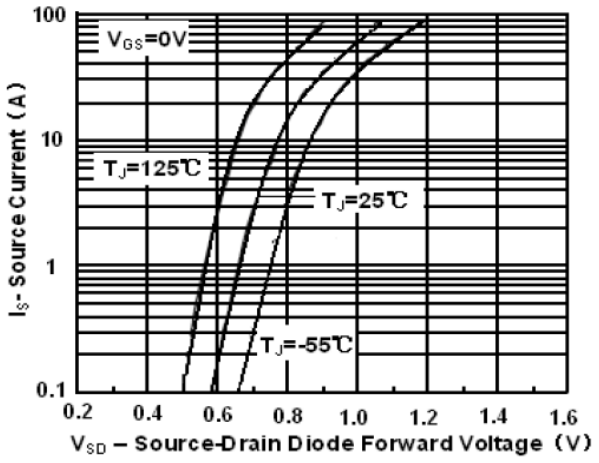


Figure 1: Body-Diode Characteristics

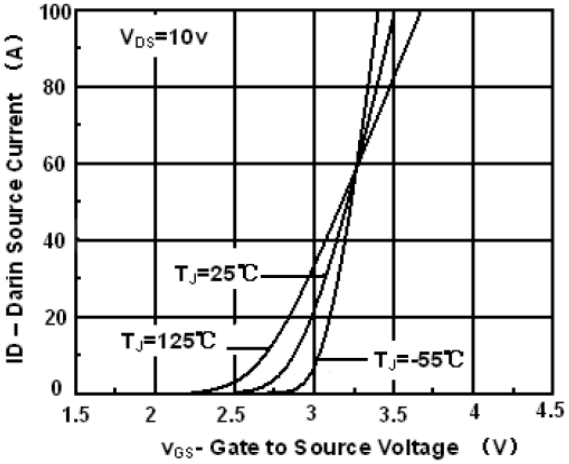


Figure 2: Typical Transfer Characteristics

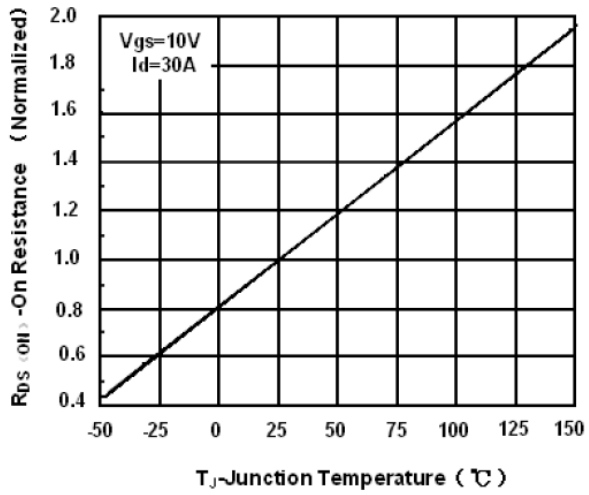


Figure 3: On-Resistance vs. Junction Temperature

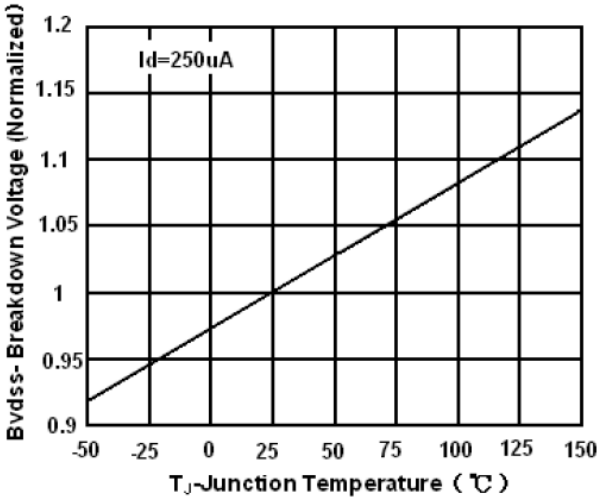


Figure 4: Breakdown Voltage vs. Junction Temperature

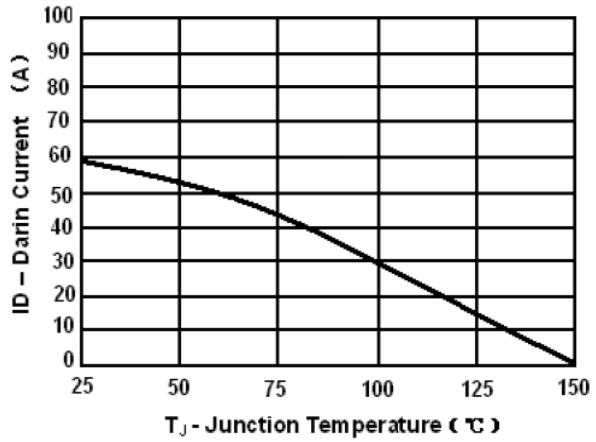


Figure 5: Maximum Drain Current vs. Junction Temperature

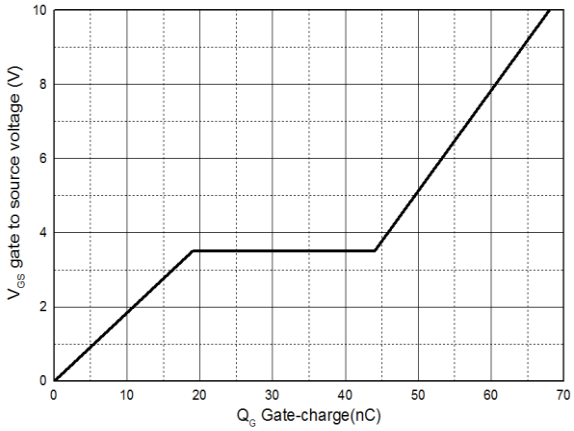


Figure 6: Gate-Charge Characteristics

Typical thermal characteristics

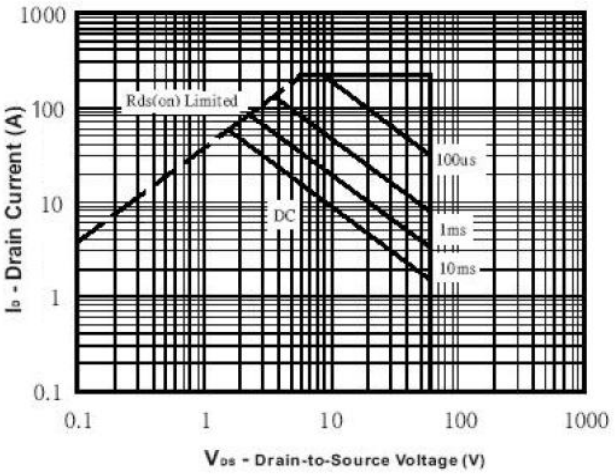


Figure 7: Safe Operation Area

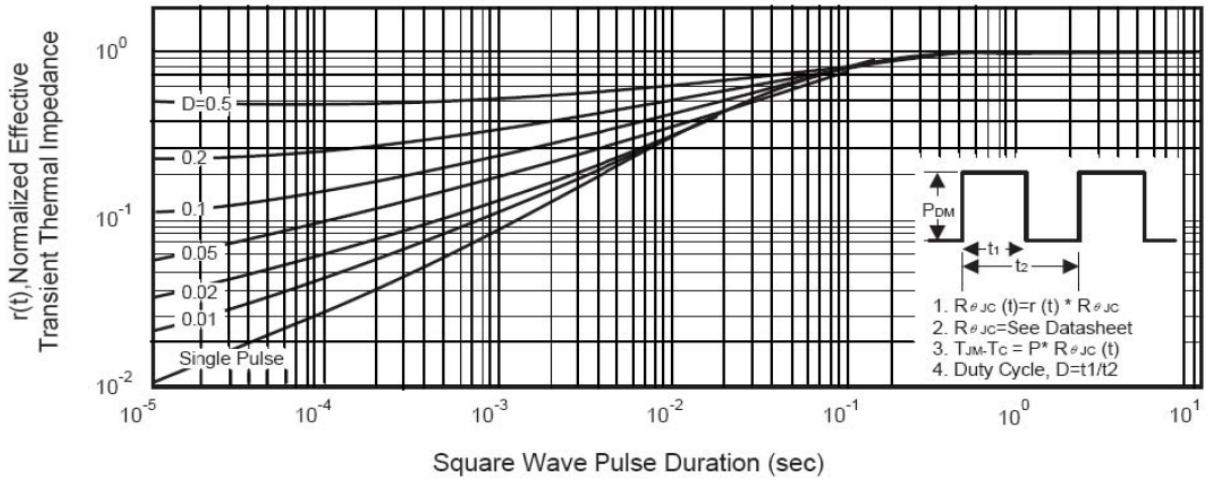
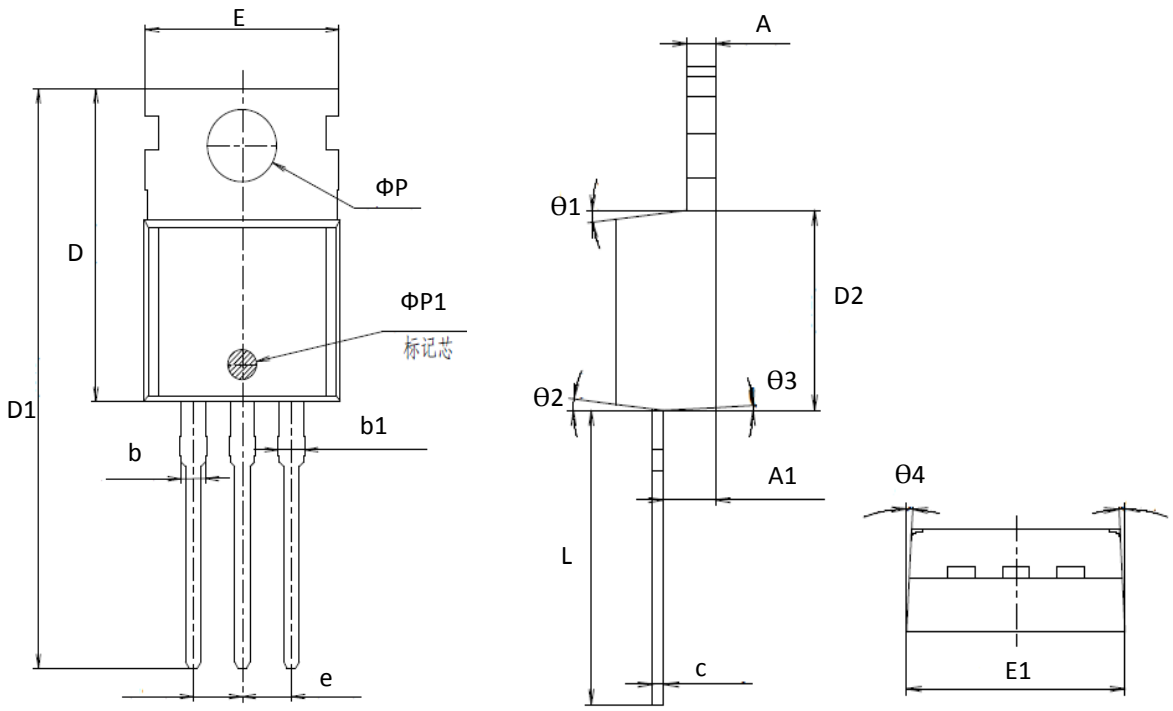


Figure 8: Normalized Thermal transient Impedance Curve

Mechanical Data：

TO220 PACKAGE OUTLINE DIMENSION_GN



Symbol	Dimension In Millimeters			Dimension In Inches		
	Min	Nom	Max	Min	Nom	Max
A	-	1.300	-	-	0.051	-
A1	2.200	2.400	2.600	0.087	0.094	0.102
b	-	1.270	-	-	0.050	-
b1	1.270	1.370	1.470	0.050	0.054	0.058
c	-	0.500	-	-	0.020	-
D	-	15.600	-	-	0.614	-
D1	-	28.700	-	-	1.130	-
D2	-	9.150	-	-	0.360	-
E	9.900	10.000	10.100	0.390	0.394	0.398
E1	-	10.160	-	-	0.400	-
ΦP	-	3.600	-	-	0.142	-
ΦP1		1.500		0.059		
e	2.54BSC			0.1BSC		
L	12.900	13.100	13.300	0.508	0.516	0.524
θ1	-	7^0	-	-	7^0	-
θ2	-	7^0	-	-	7^0	-
θ3	-	3^0	-	5^0	7^0	9^0
θ4	-	3^0	-	1^0	3^0	5^0

Ordering and Marking Information

Device Marking: SSF6114

Package (Available)

TO220

Operating Temperature Range

C : -55 to 175 ºC

Devices per Unit

Package Type	Units/ Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO220	50	20	1000	6	6000

Reliability Test Program

Test Item	Conditions	Duration	Sample Size
High Temperature Reverse Bias(HTRB)	T_j=125℃ to 175℃ @ 80% of Max V_{DSS}/V_{CES}/VR	168 hours 500 hours 1000 hours	3 lots x 77 devices
High Temperature Gate Bias(HTGB)	T_J=125℃ to 175℃ @ 100% of Max V_{GSS}	168 hours 500 hours 1000 hours	3 lots x 77 devices

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Customer Service

Worldwide Sales and Service:

Sales@silikron.com

Technical Support:

Technical@silikron.com

Suzhou Silikron Semiconductor Corp.

Building 11A Suchun Industrial Square, 428# Xinglong Street, Suzhou P.R. China

TEL: (86-512) 62560688

FAX: (86-512) 65160705

E-mail: Sales@silikron.com